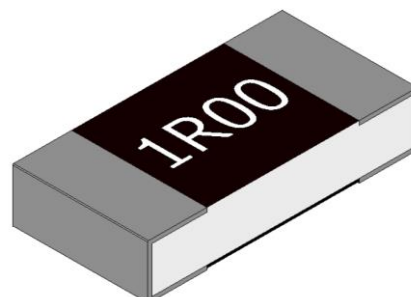


SCRR1206S1 Series Current Sensing Resistor (Lead / Halogen Free)

Features / Applications :

- High power rating is up to 1W
- RoHS compliant
- Suitable for reflow soldering

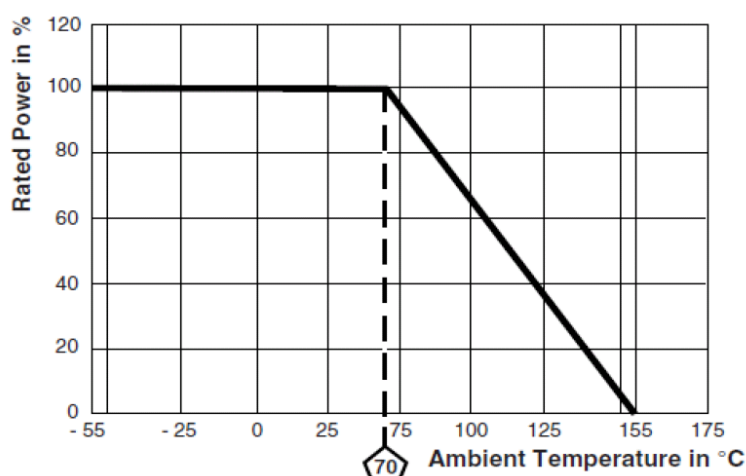


Electrical Specifications :

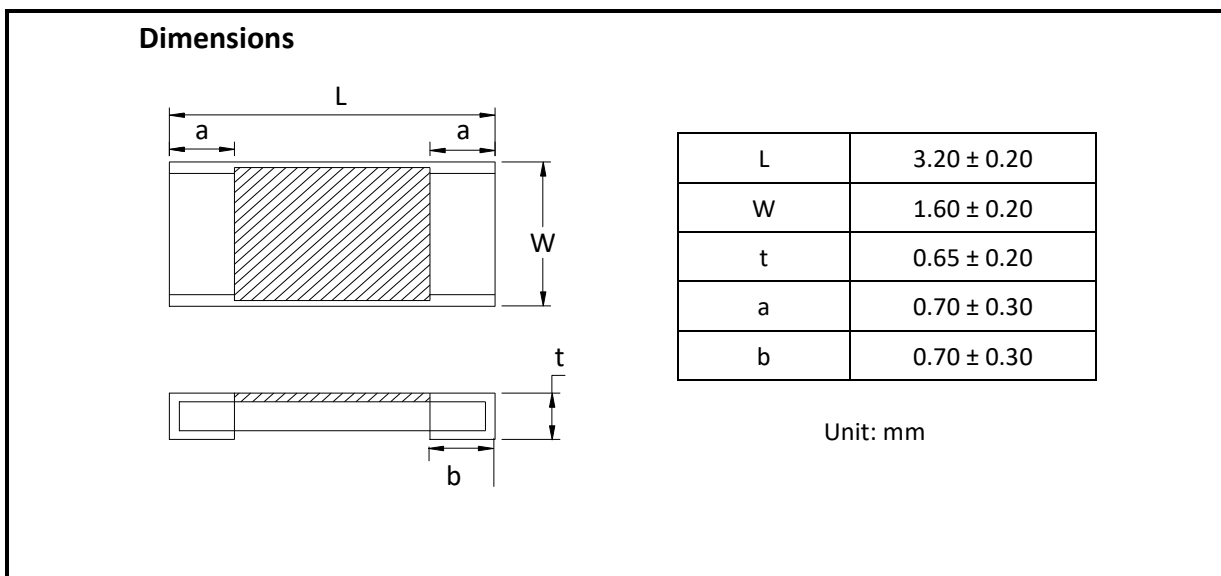
Characteristics	Feature
Power Rating*	1 W
Resistance Range	0.01Ω~1Ω
Temperature Coefficient of Resistance(ppm/°C)	±100
Resistance Tolerance	±1%(F), ±2%(G), ±5%(J)
Operation Temperature Range	-55°C ~ +155°C

*Note :

For sensor operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.



Outline Drawing :



Type Designation :

S C R R 1206 S 1 - □ □ □ □ □

(1) (2) (3) (4) - (5) (6)

Note :

- (1) Series No.
- (2) Size
- (3) Terminal type : S = Short terminal
- (4) Power Rating : 1 = 1W
- (5) Resistance value:

The "R" shall be used as a decimal point, For example --

R010 = 0.01Ω;

- (6) Tolerance (%)

F=±1%, G=±2%, J=±5%

Characteristics :

Electrical

Item	Specification and Requirement	Test Method (JIS 5201)
Temperature Coefficient of Resistance(ppm/°C)	As electrical specifications	Room temperature Room temperature +100°C
Short Time Overload	$\Delta R: \pm 0.5\%$ Without damage by flashover, spark, arcing, burning or breakdown	2.5 x rated power for 5 seconds
Insulation Resistance	Over 100 M Ω on Overcoat layer face up Over 1,000 M Ω on Substrate side face up	(1) Setup as figure 1 (2) Test voltage: 100VDC \pm 15VDC (3) Test time: 60 + 10 / - 0 seconds
Voltage Proof	Resistance range: $\pm 1.0\%$ Without damage by flashover, spark, arcing, burning or breakdown	(1) Setup as figure 1 (2) Test voltage: 400VAC(rms.) (3) Test time: 60 + 10 / - 0 seconds

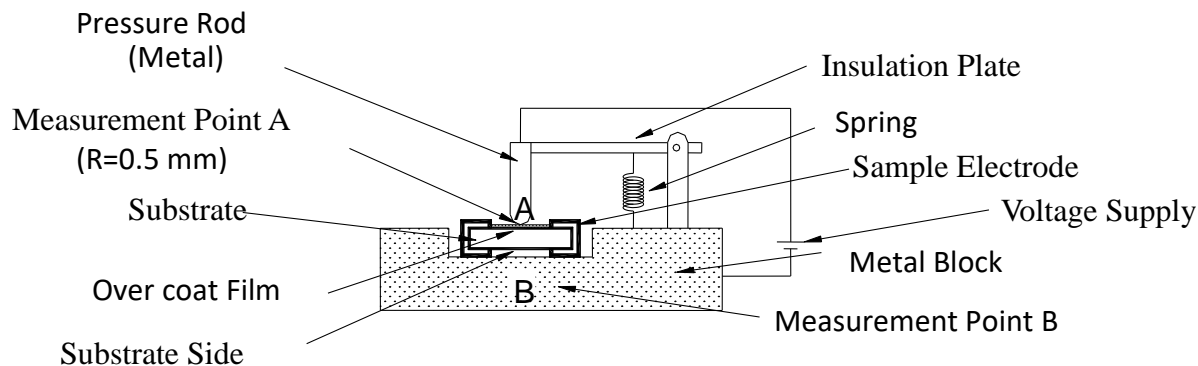


Figure 1 : Measurement Setup

Mechanical

Item	Specification and Requirement	Test Method (JIS 5201)
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	Solder bath: After immersing in flux, dip in 245 \pm 5°C molten solder bath for 2 \pm 0.5 seconds

Item	Specification and Requirement	Test Method (JIS 5201)
Resistance to Solder Heat	$\Delta R: \pm 1.0\%$ Without distinct deformation in appearance	(1) Pre-heat: $100 \sim 110^{\circ}\text{C}$ for 30 seconds (2) Immersed at solder bath of $270 \pm 5^{\circ}\text{C}$ for 10 ± 1 seconds
Bending Test	$\Delta R: \pm 1.0\%$ Without mechanical damage such as break	Bending value: 3 mm for 30 ± 1 seconds
Solvent Resistance	Without mechanical and distinct damage in appearance	(1) Solvent: Trichloroethane or Isopropyl alcohol (2) Immersed in solvent at room temperature for 300 seconds

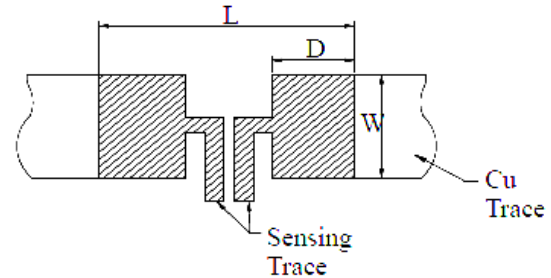
Endurance

Item	Specification and Requirement	Test Method (JIS 5201)
Rapid Change of Temperature	$\Delta R: \pm 1.0\%$ Without distinct damage in appearance	$-55 \sim 125^{\circ}\text{C}$ 100cycles, 15 min at each extreme condition
Moisture with Load	$\Delta R: \pm 5.0\%$ Without distinct damage in appearance	$40 \pm 2^{\circ}\text{C}$ with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 0.5 hours OFF. Cycle repeated 1,000 hours
Load Life	$\Delta R: \pm 5.0\%$ Without distinct damage in appearance	Rated voltage for 1.5 hours followed by a pause 0.5 hour at $70 \pm 2^{\circ}\text{C}$. Cycle repeated 1000 hours
Low Temperature Store	$\Delta R: \pm 5.0\%$ Without distinct damage in appearance	Store temperature: $-55 \pm 3^{\circ}\text{C}$ for total 1,000 hours
High Temperature Store	$\Delta R: \pm 5.0\%$ Without distinct damage in appearance	Store temperature: $150 \pm 2^{\circ}\text{C}$ for total 1,000 hours

Recommend Land Pattern Dimensions :

	W (mm)	L (mm)	D (mm)	t (μ m)
1632	1.78	4.14	1.37	105

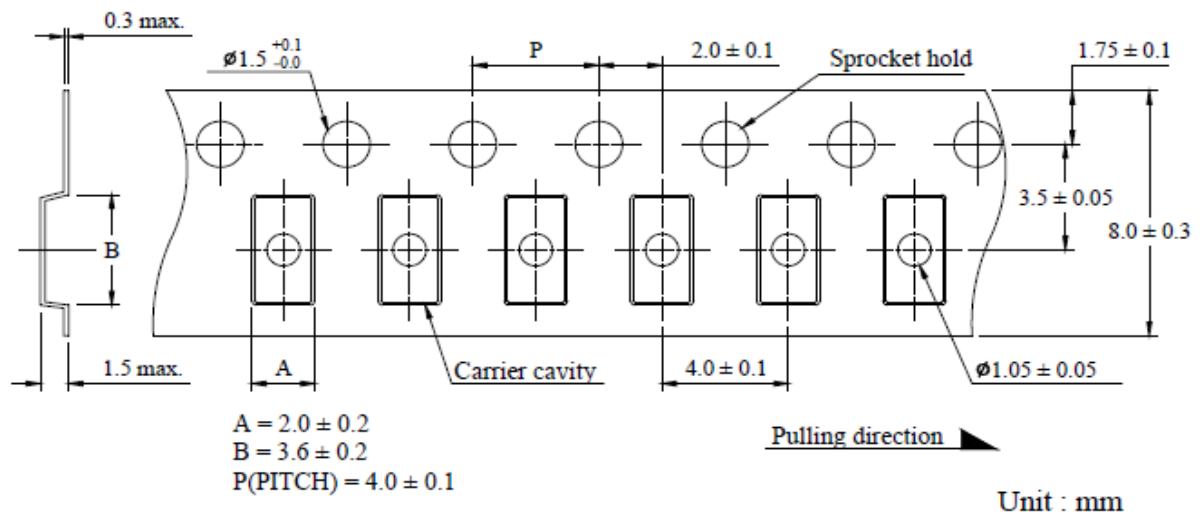
t: Copper foil minimum thickness of PCB



Notice: We recommend there is no circuit design between pads to avoid circuit short.

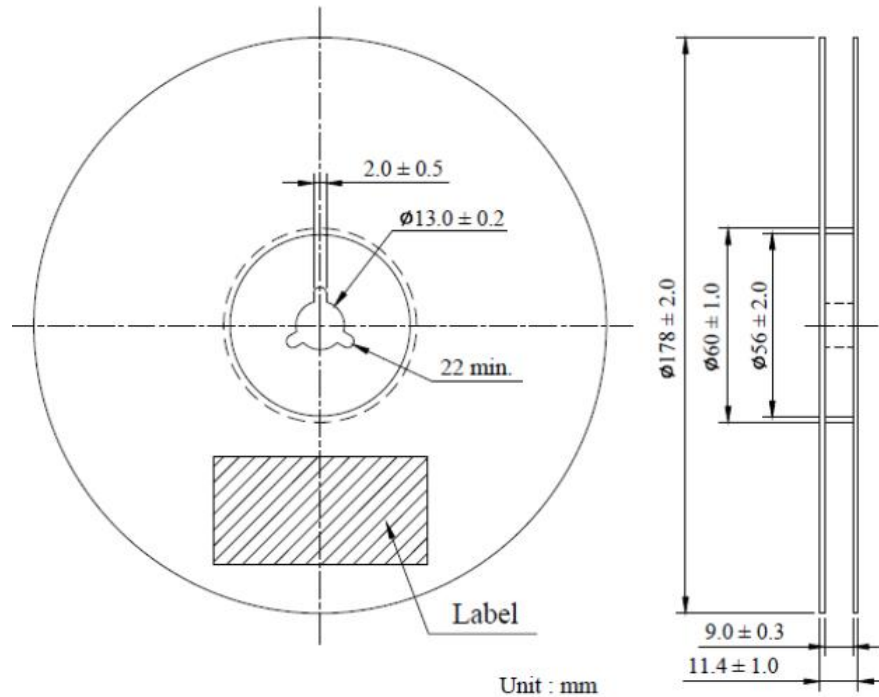
Packaging :

Tape packaging dimensions



Remark: Leader tape length ≥ 30 cm (150 Hollow carrier cavity)

Reel dimensions



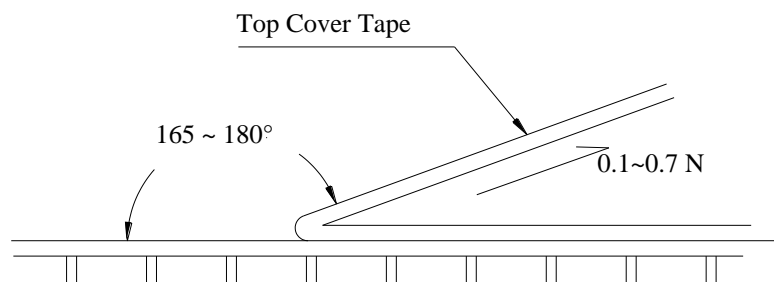
Numbers of Taping : 4,000 pieces /reel

The following items shall be marked on the reel.

- (1) Type designation.
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name

Peel force of top cover tape

The peel speed shall be about 300 mm/min. The peel force of top cover tape shall be between 0.1 to 0.7 N.



Care Note :

Care note for storage

- (1) Chip resistor shall be stored in a room where temperature and humidity must be controlled.
(temperature 5 to 35°C, humidity 45 to 85% RH) However, a humidity keep it low, as it is possible.
- (2) Chip resistor shall be stored as direct sunshine doesn't hit on it.
- (3) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (Chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen).

Care note for operating and handling

- (1) It is necessary to protect the edge and protection coat of resistors from mechanical stress.
- (2) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (3) Resistors shall be used with in rated range shown in specification. Especially, if voltage more than specified value will be loaded to resistor, there is a case it will make damage for machine because of temperature rise depending on generating of heat, and increase resistance value or breaks.
- (4) In case that resistor is loaded a rated voltage, it is necessary to confirms temperature of a resistor and to reduce a load power according to load reduction curve, because a temperature rise of a resistor depends on influence of heat from mounting density and neighboring element.
- (5) Observe Limiting element voltage and maximum overload voltage specified in each specification
- (6) If there is possibility that a large voltage (pulse voltage, shock voltage) charge to resistor, it is necessary that operating condition shall be set up before use.